

ABSTRACT

Provided is a method of manufacturing a semiconductor device that can reduce the positional deviation of an electronic component and can reduce embedding of the electronic component in a pressure-sensitive adhesive sheet. The present invention relates to a method of manufacturing a semiconductor device, the method including a laminating step of disposing a resin sheet on an electronic component temporarily fixing body including a pressure-sensitive adhesive sheet and a plurality of electronic components that are arranged on the pressure-sensitive adhesive sheet; and a sealing step of pressing a laminate obtained in the laminating step at 0.03 to 3 MPa to form a sealed body including the plurality of electronic components and the resin sheet that covers the plurality of electronic components.